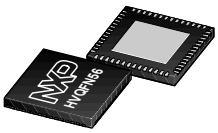


SOT684-13

HVQFN56, plastic thermal enhanced very thin quad flat package; no leads; 56 terminals; body 8 mm x 8 mm x 0.85 mm

13 October 2017 Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN56
Package type industry code	HVQFN56
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	13-7-2015
Manufacturer package code	SOT684-13

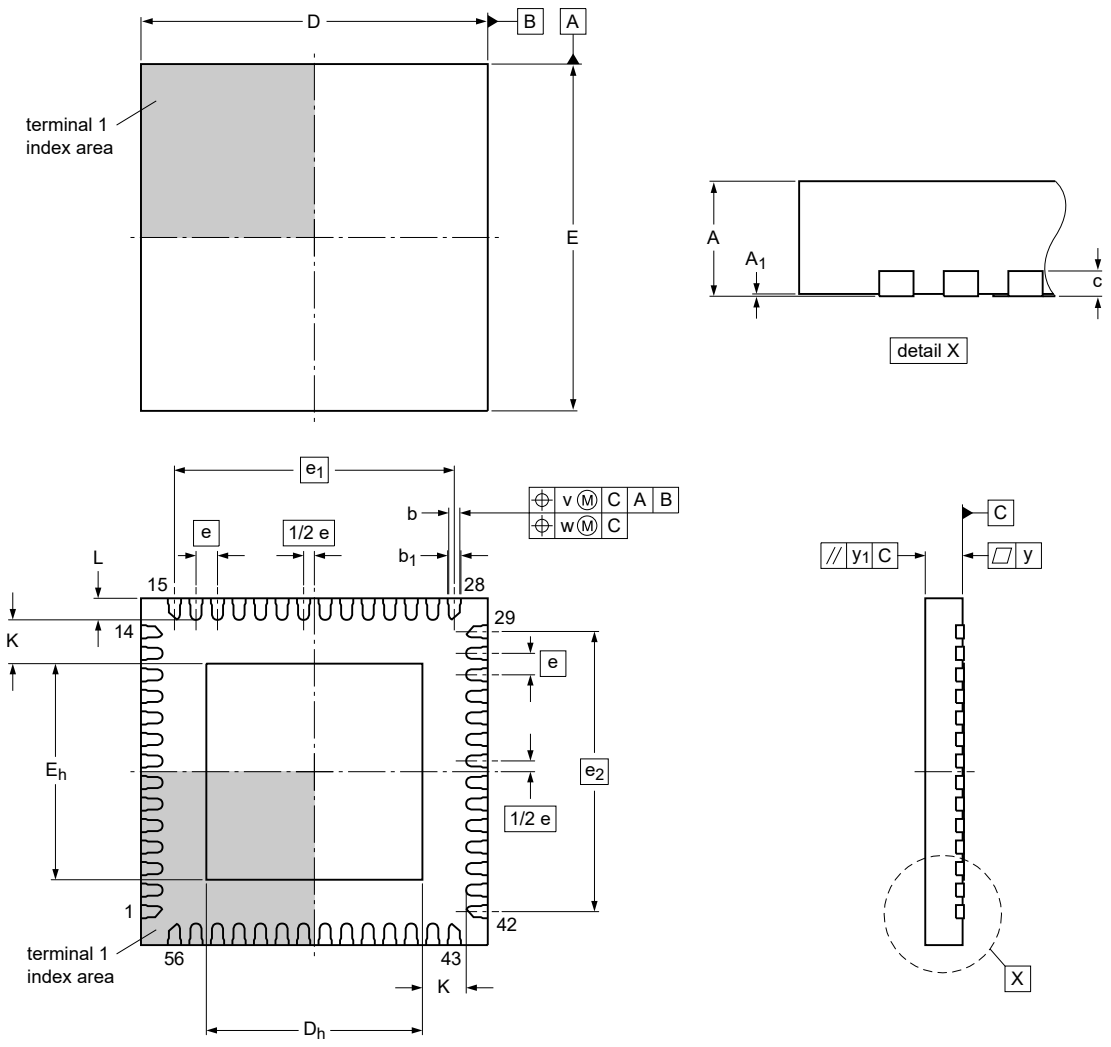
Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		7.9	-	8	8.1	mm
E	package width		7.9	-	8	8.1	mm
A	seated height		0.8	-	0.85	1	mm
e	nominal pitch		-	-	0.5	-	mm
n_2	actual quantity of termination		-	-	56	-	A/A

HVQFN56, plastic thermal enhanced very thin quad flat package; no leads; 56 terminals; body 8 mm x 8 mm x 0.85 mm

2. Package outline

HVQFN56: plastic thermal enhanced very thin quad flat package; no leads; 56 terminals; body 8 x 8 x 0.85 mm **SOT684-13**



Dimensions (mm are the original dimensions)

Unit		$A^{(1)}$	A_1	b	b_1	c	$D^{(1)}$	D_h	$E^{(1)}$	E_h	e	e_1	e_2	L	K	v	w	y	y_1
	max	1.00	0.05	0.30	0.32		8.1	5.15	8.1	5.15				0.6					
mm	nom	0.85	0.02	0.25	0.27	0.2	8.0	5.00	8.0	5.00	0.5	6.5	6.5	0.5		0.1	0.05	0.05	0.1
	min	0.80	0.00	0.20	0.22		7.9	4.85	7.9	4.85				0.4	0.8				

Note
1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot684-13_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT684-13		- - -				~~15-05-29~~ 15-07-13

Fig. 1. Package outline HVQFN56 (SOT684-13)

3. Soldering

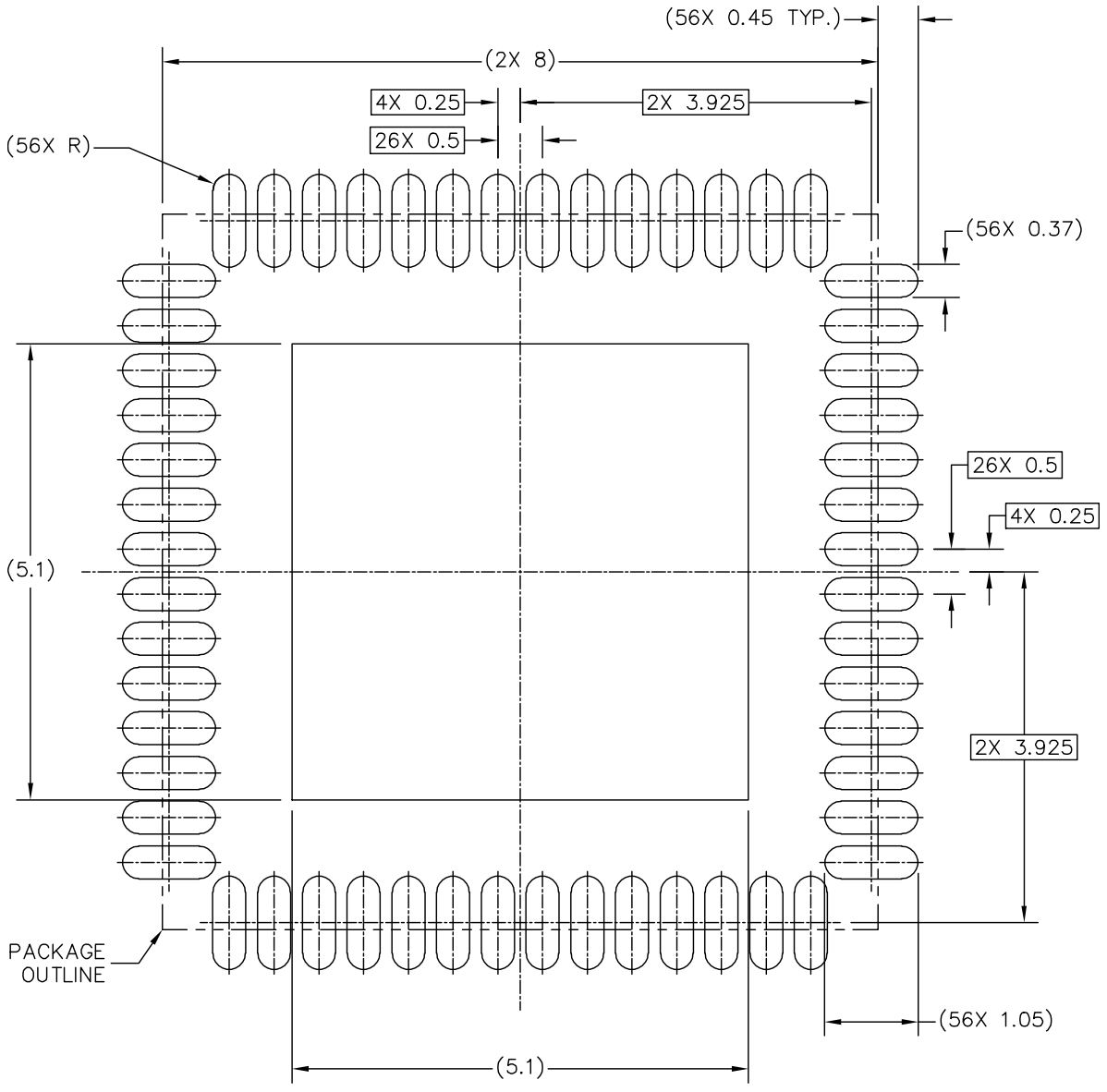
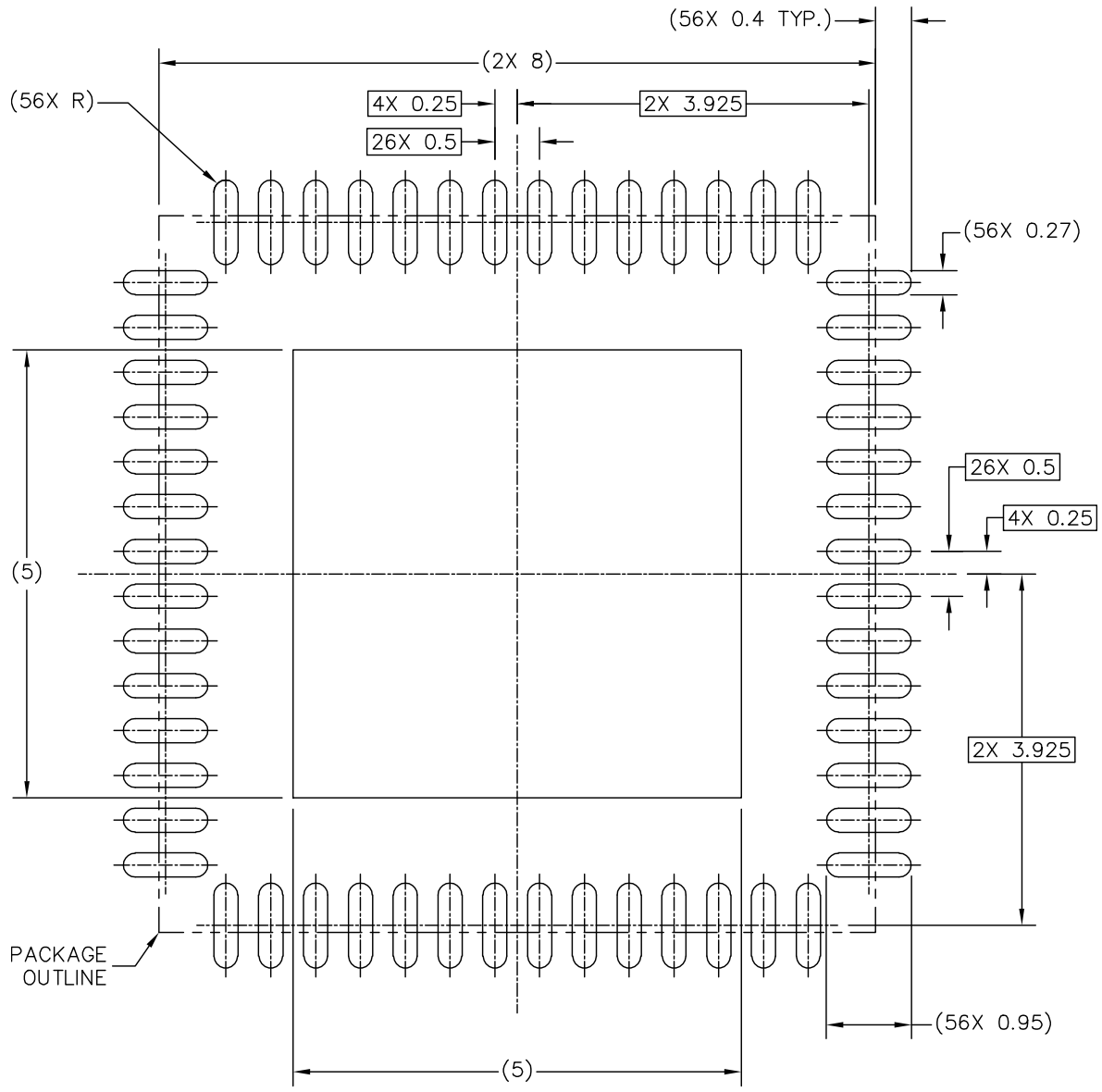


Fig. 2. Reflow soldering footprint for HVQFN56 (SOT684-13)

HVQFN56, plastic thermal enhanced very thin quad flat package; no leads; 56 terminals; body 8 mm x 8 mm x 0.85 mm



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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 DATE: 25 AUG 2017

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: SOT684–13	REVISION: 0	PAGE:

Fig. 3. Reflow soldering footprint part 2 for HVQFN56 (SOT684-13)

HVQFN56, plastic thermal enhanced very thin quad flat package; no leads; 56 terminals; body 8 mm x 8 mm x 0.85 mm

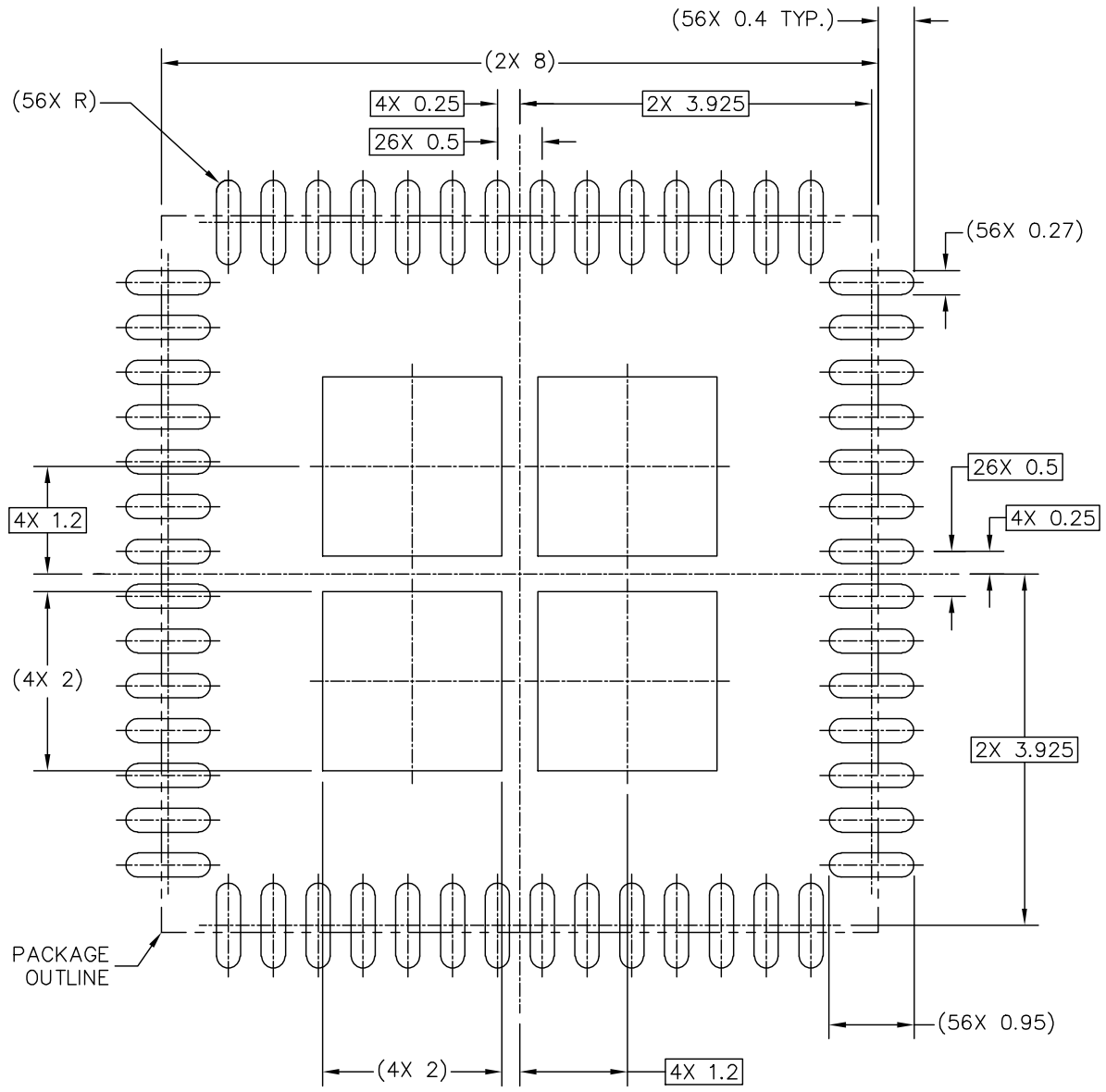

Fig. 4. Reflow soldering footprint part 3 for HVQFN56 (SOT684-13)

4. Legal information

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5. Contents

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Date of release: 13 October 2017